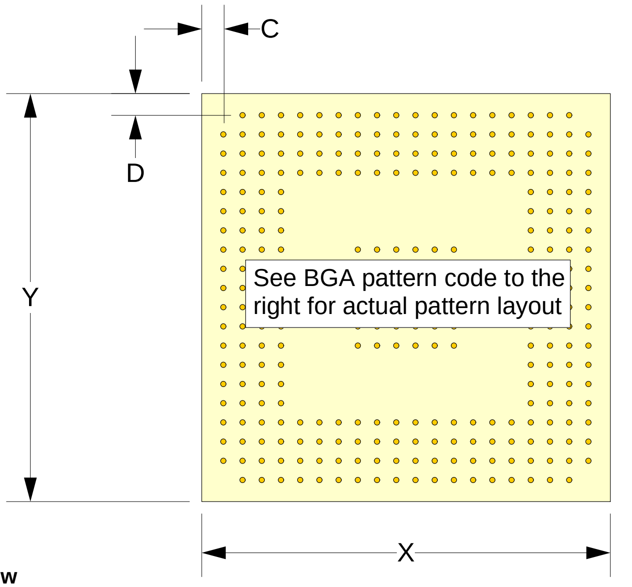
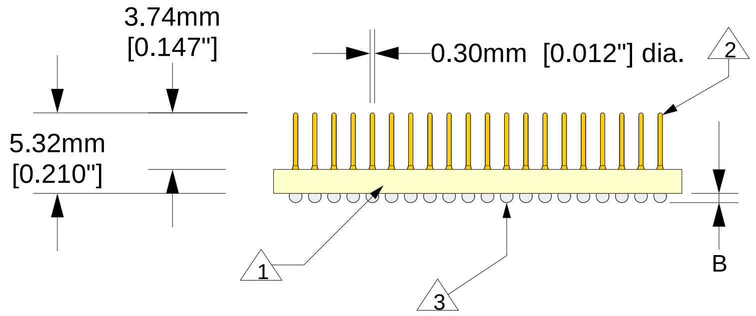


Top View
(reference only)

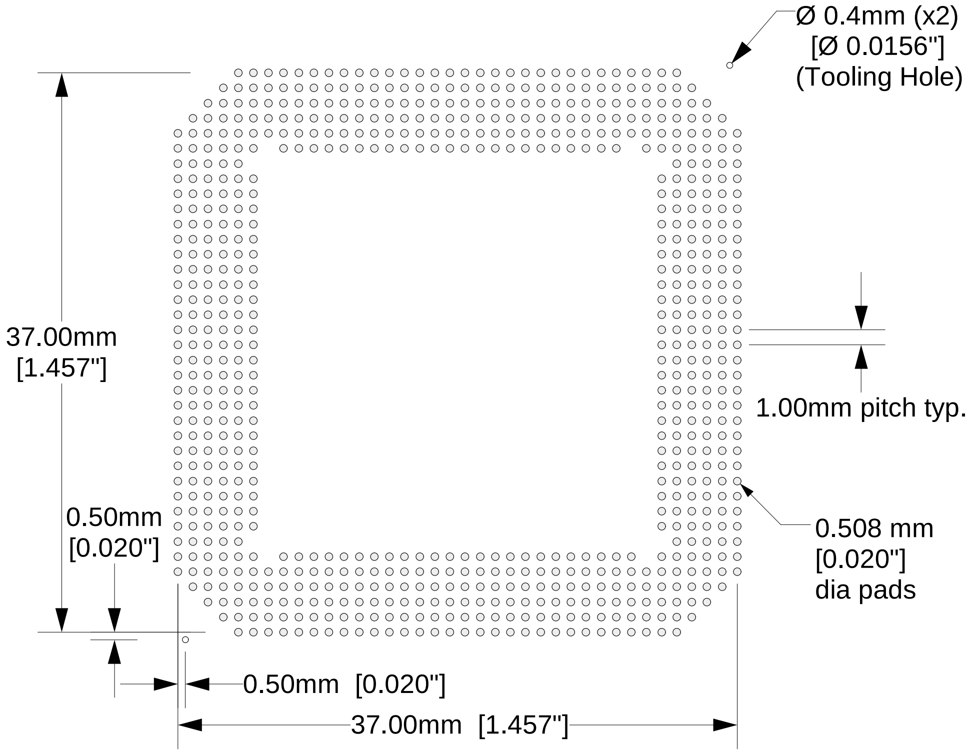


Side View
(reference only)

Note: SMT foot is independent of actual BGA package thickness.

1. Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. SnPb plating.
2. Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
3. Balls: Eutectic 63/37 SnPb.

Package Code: BGA720A



Top View: Recommended PCB Layout
Scale: 2:1

Pin Count	720
Array Size	38X38
Pitch	1 mm
Body size (XxY)	40mm X 40mm
MGA Location (CxD)	1.5mm X 1.5mm
Ball Thickness (B)	0.024

Description: <u>BGA Emulator Foot (solder base)</u>.
720 position terminal pins (UGA, Ultra Minigrid Array) to SM balls. Surface mounts to target BGA land pattern.

SF-BGA720A-B-11 Drawing	Status: Released	Scale -	Rev: B
© 2000 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: K Gilbertson	Date: 05/25/00	
	File: SF-BGA720A-B-11 Dwg.mcd	Modified: 1/13/03	

Tolerances: diameters ±0.03mm [±0.001"],
PCB perimeters ±0.13mm [±0.005"],
PCB thicknesses ±0.18mm [±0.007"],
pitches (from true position) ±0.08mm [±0.003"],
all other tolerances ±0.13mm [±0.005"]
unless stated otherwise. Materials and specifications are subject to change without notice.